

Data sheet acquired from Harris Semiconductor SCHS040D - Revised October 2003

### CMOS

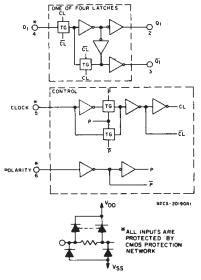
## Quad Clocked "D" Latch

High-Voltage Types (20-Volt Rating)

■ CD4042B types contain four latch circuits, each strobed by a common clock. Complementary buffered outputs are available from each circuit. The impedance of the n- and p-channel output devices is balanced and all outputs are electrically identical.

Information present at the data input is transferred to outputs Q and Q during the CLOCK level which is programmed by the POLARITY input. For POLARITY = 0 the transfer occurs during the 0 CLOCK level and for POLARITY = 1 the transfer occurs during the 1 CLOCK level. The outputs follow the data input providing the CLOCK and POLARITY levels defined above are present. When a CLOCK transition occurs (positive for POLARITY = 0 and negative for POLARITY = 1) the information present at the input during the CLOCK transition is retained at the outputs until an opposite CLOCK transition occurs.

The CD4042B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffixes), 16-lead dual-in-line plastic package (E suffix), 16-lead small-outline packages (D, DR, DT, DW, DWR, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).



CLOCK	POLARITY	Q
0	0	D
	0	LATCH
1	1	D
	1	LATCH

Fig. 1 - Logic block diagram and truth table.

# CD4042B Types

#### Features:

- Clock polarity control

  Q and Q outputs
- Common clock
- Low power TTL compatible
- Standardized symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 µA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- 5-V, 10-V, and 15-V parametric ratings
- Noise margin (over full package temperature range):

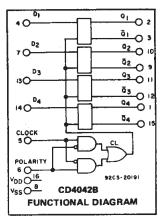
1 V at VDD = 5 V

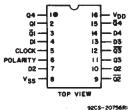
2 V at V<sub>DD</sub> = 10 V 2.5 V at V<sub>DD</sub> = 15 V

■ Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

#### Applications:

- Buffer storage
- Holding register
- General digital logic





**TERMINAL ASSIGNMENT** 

### STATIC ELECTRICAL CHARACTERISTICS

CHARAC- TERISTIC		OITIO		LIMI	TS AT	INDIÇA	TED TE	MPERA	TURES (	°C)	UNITS
12	٧o	VIN	V <sub>DD</sub>						+25		
	(V)	(V)	(V)	-55	-40	+85	+125	Min.	Тур.	Max.	
Quiescent		0,5	5	1	1	30	30	<u> </u>	0.02	1	
Device		0,10	10	2	.2	60	60	_	0.02	2	μА
Current		0,15	15	4	4	120	120		0.02	4	, m. T.
I <sub>DD</sub> Max.		0,20	20	20	20	600	600		0.04	20	
Output Low											
(Sink)	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	11		
Current,	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6		
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	-	mΑ
Output High	4.6	0,5	5	-0.64	-0.61	-0.42			-1	_	
(Source)	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2		
Current,	9.5	0,10	10	-1.6	-1.5	-1.1	0.9	-1.3	-2.6	. —	
I <sub>OH</sub> Min.	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	6.8	-	
Output Volt-						•					
age:		0,5	5		0.0				, 0	0.05	
Low-Level,		0,10	10		0.0	)5		<u> </u>	0	0.05	
VOL Max.	_	0,15	15		0.0	)5		_	0	0.05	v
Output Volt-											ľ
age:	_	0,5	5	3.45	4.9	95		4.95	- 5		
High-Level,		0,10	10		9.9	95		9.95	10	_	ŀ
V <sub>OH</sub> Min.	_	0,15	15		14.	95		14.95	15	- 1	
Input Low	0.5,4.5	_	5		1.	5		-	_	1.5	
Voltage,	1,9	_	10			3	1.	-	_	3	
VIL Max.	1.5,13.5		15		4			-	-	4	v
Input High	0.5,4.5	_	5		3.	5		3.5	_	_	"
Voltage,	1,9	_	10			1		7		_	
VIH Min.	1.5,13.5	-	15		1	1		11	-	-	
Input Current, I <sub>IN</sub> Max.	-	0,18	18	±0.1	±0.1	±1	±1	_	±10-5	±0.1	μΑ

## CD4042B Types

MAXIMUM RATINGS, Absolute-Maximum Values:	
DC SUPPLY-VOLTAGE RANGE, (VDD)	
Voltages referenced to VSS Terminal)	
INPUT VOLTAGE RANGE, ALL INPUTS	0.5V to Vnn +0.5V
DC INPUT CURRENT, ANY ONE INPUT	±10mA
POWER DISSIPATION PER PACKAGE (PD):	
For T <sub>A</sub> = -55°C to +100°C	500mW
For T <sub>A</sub> = +100°C to +125°C	Derate Linearity at 12mW/OC to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	,
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package	Types)
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package OPERATING-TEMPERATURE RANGE (TA)	Types)100mW
OPERATING-TEMPERATURE RANGE (TA)	55°C to +125°C
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package OPERATING-TEMPERATURE RANGE (T <sub>A</sub> )	55°C to +125°C

RECOMMENDED OPERATING CONDITIONS at  $T_A = 25^{\circ}$ C, Except as Noted. For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	V <sub>DD</sub>	LIN	UNITS	
	(V)	Min.	Max.	1
Supply-Voltage Range (For TA=Full Package Temperature Range)	_	3	18	v
	5	200	_	
Clock Pulse Width, tw	10	100	-	ns
	15	60	-	
	5	50		
Setup Time, t <sub>S</sub>	10	30	-	ns
	15	25	L–	
	5	120	_	
Hold Time, tH	10	60	-	ns
	15	50	_	
Clock Rise or Fall Time: t <sub>r</sub> , t <sub>f</sub>	5,10 15		e or fall insitive.	μS

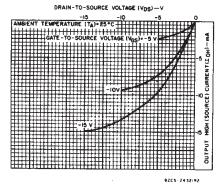


Fig. 5 — Minimum output high (source) current characteristics.

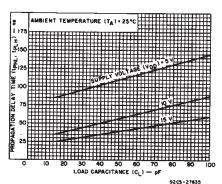


Fig. 6 - Typical propagation delay time vs. load capacitance—data to Q.

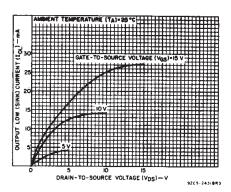


Fig. 2 – Typical output low (sink) current characteristics.

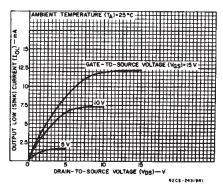


Fig. 3 — Minimum output low (sink) current characteristics.

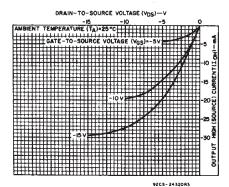


Fig. 4 — Typical output high (source) current characteristics.

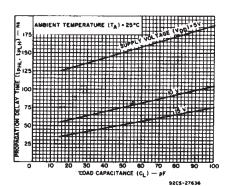


Fig. 7 — Typical propagation delay time vs. load capacitance—data to  $\overline{\Omega}$ .

### CD4042B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at T<sub>A</sub> = 25°C; Input t<sub>r</sub> , t<sub>f</sub> = 20 ns, C<sub>L</sub> = 50 pF, R<sub>L</sub> = 200 K $\Omega$ 

CHARACTERISTIC	V <sub>DD</sub>	LIM	UNITS		
	( ( )	Тур.	Max.		
Propagation Delay	5	110	220		
Time: tpHL , tpLH	10	55	110	ns	
Data In to Q	15	40	80	l .	
	5	150	300		
Data In to Q	10	75	150	ns	
	15	50	100		
	5	225	450		
Clock to Q	10	100	200	ns	
	15	80	160		
	5	250	500	1	
Clock to Q	10	115	230	ns	
	15	90	180		
Transition	5	100	200		
Time: tTHL, tTLH	10	50	100	ns	
· ····································	15	40	80	l	
Minimum Clock	5	100	200		
Pulse Width, tw	10	50	100	ns	
	15	30	60		
	5	60	120		
Minimum Hold Time, tH	10	30	60	ns	
	15	25	50		
Minimum Setup	5	0	50		
Time, ts	10	0	30	ns	
rine, tg	15	0	25		
Clock Input Rise or Fall	5,10	Not rise	or fall		
Time: t <sub>r</sub> , t <sub>f</sub>	15	time se	nsitive.	μS	
Input Capacitance, CIN		5	7.5	ρF	
Polarity Input		Ŭ	7.5	۳,	
All Other Inputs	-	7.5	15	pF	

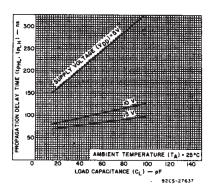


Fig. 8 - Typical propagation delay time vs. load capacitance-clock to Q

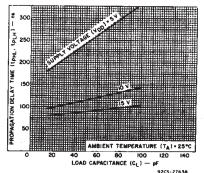
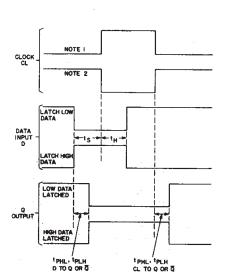


Fig. 9 — Typical propagation delay time vs. load capacitance—clock to  $\overline{\mathbf{Q}}$ .



NOTES: 1. FOR POSITIVE CLOCK EDGE, INPUT DATA IS LATCHED WHEN POLARITY IS LOW.

2. FOR NEGATIVE CLOCK EDGE, INPUT DATA IS LATCHED WHEN POLARITY IS NIGH.

92cs-27630 Fig. 12 - Dynamic test parameters.

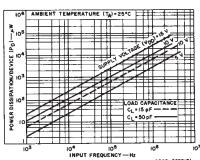


Fig. 10 – Typical power dissipation vs. frequency.

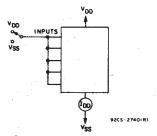


Fig. 13 - Quiescent device current test circuit.

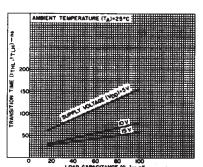


Fig. 11 — Typical transition time vs. load capacitance.

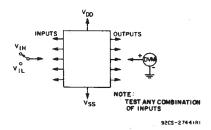


Fig. 14 - Input voltage test circuit.

## CD4042B Types

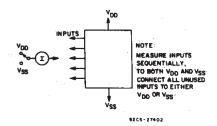
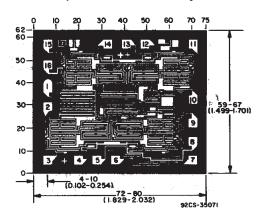


Fig. 15 - Input current test circuit.

#### Chip Dimensions and Pad Layout



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils  $(10^{-3} \text{ inch})$ .





ti.com 28-Feb-2005

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD4042BD	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
CD4042BDR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
CD4042BDT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
CD4042BDW	ACTIVE	SOIC	DW	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR Level-1-235C-UNLIM
CD4042BDWR	ACTIVE	SOIC	DW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR Level-1-235C-UNLIM
CD4042BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4042BF	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4042BF3A	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4042BM	OBSOLETE	SOIC	D	16		None	Call TI	Call TI
CD4042BNSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
CD4042BPW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4042BPWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

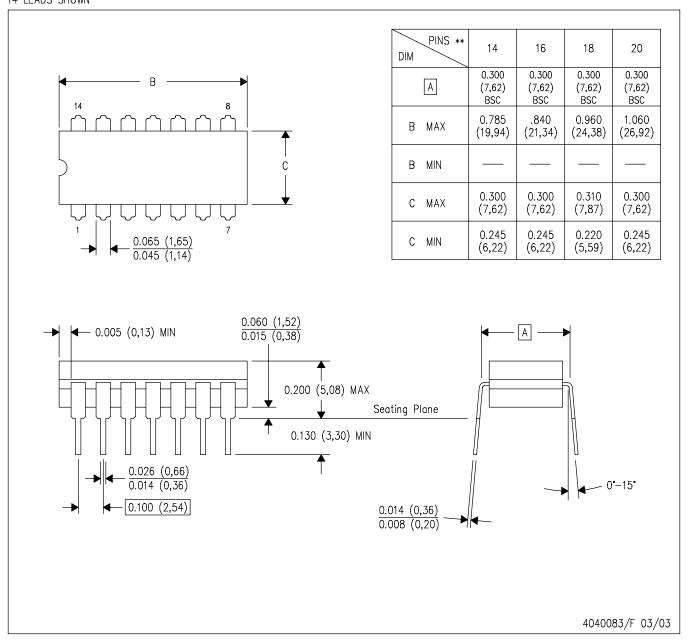
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

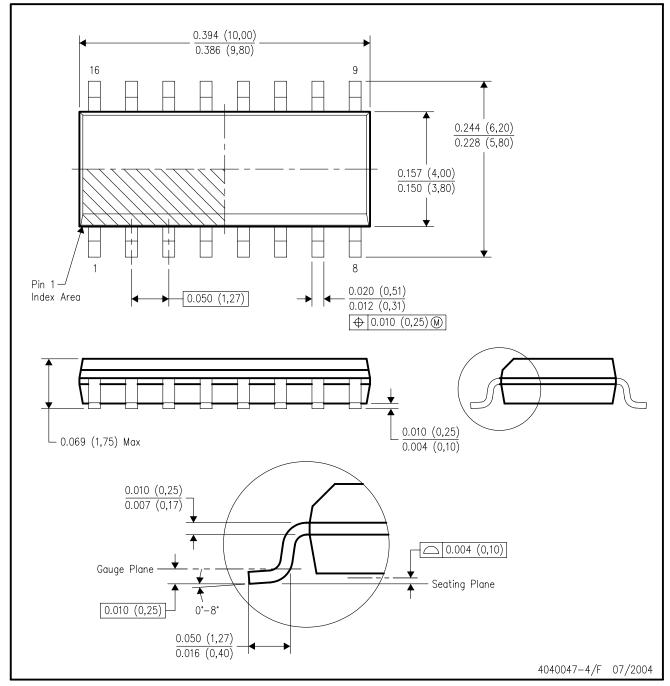


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDSO-G16)

## PLASTIC SMALL-OUTLINE PACKAGE

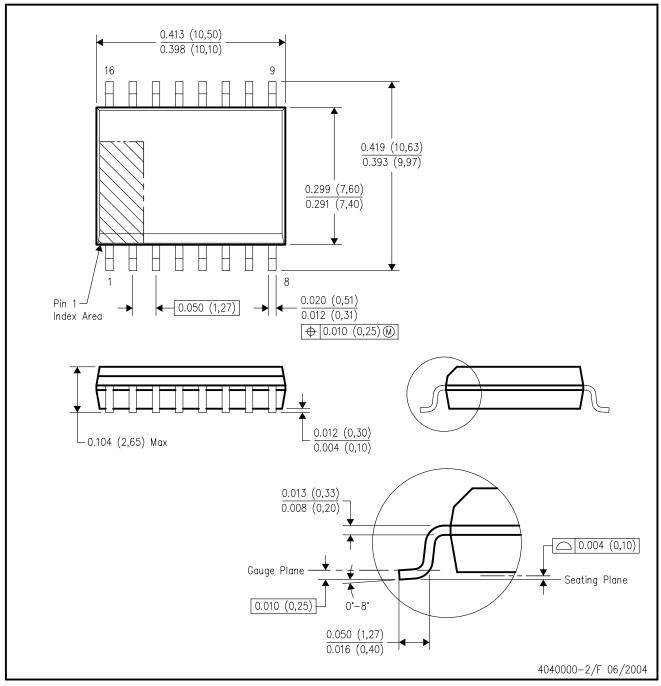


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



# DW (R-PDSO-G16)

## PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AA.



### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



### PW (R-PDSO-G\*\*)

### 14 PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated

This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.

## **Texas Instruments**

http://www.ti.com

This file is the datasheet for the following electronic components:

CD4042BF - http://www.ti.com/product/cd4042bf?HQS=TI-null-null-dscatalog-df-pf-null-wwe
CD4042B - http://www.ti.com/product/cd4042b?HQS=TI-null-null-dscatalog-df-pf-null-wwe
CD4042BPW - http://www.ti.com/product/cd4042bpw?HQS=TI-null-null-dscatalog-df-pf-null-wwe
CD4042BD - http://www.ti.com/product/cd4042bd?HQS=TI-null-null-dscatalog-df-pf-null-wwe
CD4042BDR - http://www.ti.com/product/cd4042bdr?HQS=TI-null-null-dscatalog-df-pf-null-wwe
CD4042BE - http://www.ti.com/product/cd4042be?HQS=TI-null-null-dscatalog-df-pf-null-wwe
CD4042BPWR - http://www.ti.com/product/cd4042bpwr?HQS=TI-null-null-dscatalog-df-pf-null-wwe
CD4042BM - http://www.ti.com/product/cd4042bdwr?HQS=TI-null-null-dscatalog-df-pf-null-wwe
CD4042BDWR - http://www.ti.com/product/cd4042bdwr?HQS=TI-null-null-dscatalog-df-pf-null-wwe
CD4042BDW - http://www.ti.com/product/cd4042bdw?HQS=TI-null-null-dscatalog-df-pf-null-wwe
CD4042BDW - http://www.ti.com/product/cd4042bdw?HQS=TI-null-null-dscatalog-df-pf-null-wwe
CD4042BDW - http://www.ti.com/product/cd4042bdw?HQS=TI-null-null-dscatalog-df-pf-null-wwe
CD4042BDT - http://www.ti.com/product/cd4042bdt?HQS=TI-null-null-dscatalog-df-pf-null-wwe
CD4042BNSR - http://www.ti.com/product/cd4042bnsr?HQS=TI-null-null-dscatalog-df-pf-null-wwe